



SSC8623GN4

N and P-Channel Enhancement Mode Power MOSFET

➤ Features

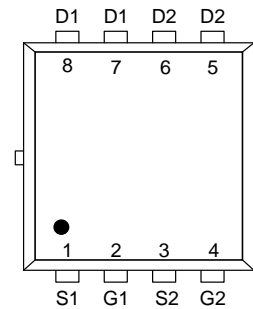
N-Channel

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
20V	$\pm 12V$	14m Ω @4V5	21A
		17m Ω @2V5	

P-Channel

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
-20V	$\pm 12V$	24m Ω @-4V5	-18A
		37m Ω @-2V5	

➤ Pin configuration

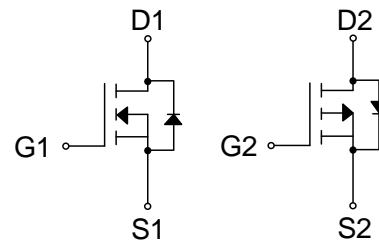


PDFN3.3X3.3-8L (Top View)

➤ Description

The SSC8623GN4 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

100% UIS + ΔV_{DS} + R_g Tested!



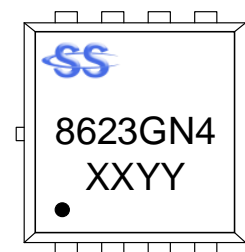
Pin Configuration

➤ Applications

- PWM Applications
- Load Switch
- DC-DC Converters
- Wireless Chargers

➤ Ordering Information

Device	Package	Shipping
SSC8623GN4	PDFN3.3X3.3-8L	5000/Reel



Marking

(XXYY: Internal Traceability Code)



➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-to-Source Voltage		V_{DSS}	20	-20	V
Gate-to-Source Voltage		V_{GSS}	± 12	± 12	V
Continuous Drain Current ^a	$T_A=25^{\circ}\text{C}$	I_D	21	-18	A
	$T_A=100^{\circ}\text{C}$		12	-10	A
Pulsed Drain Current ^b		I_{DM}	80	-65	A
Power Dissipation ^a		P_{DSM}	2.5	2.5	W
Avalanche Energy ^b L=0.5mH Single Pulse		E_{AS}	25	25	mJ
Power Dissipation ^c	$T_A=25^{\circ}\text{C}$	P_D	11.4	11.4	W
	$T_A=100^{\circ}\text{C}$		4.6	4.6	W
Operation junction temperature		T_J	-55 to 150	-55 to 150	$^{\circ}\text{C}$
Storage temperature range		T_{STG}	-55 to 150	-55 to 150	$^{\circ}\text{C}$

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	N-Channel	P-Channel	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	50	50	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	11	10	

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.



➤ **N-Channel Electrical Characteristics (T_A=25°C unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	0.5	0.7	1	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 4A		14	21	mΩ
		V _{GS} = 2.5V, I _D = 3A		17	25	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 1A			1.3	V
Input Capacitance	C _{ISS}	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz		710		pF
Output Capacitance	C _{OSS}			112		
Reverse Transfer Capacitance	C _{RSS}			100		
Total Gate Charge	Q _G	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 3A		9		nC
Gate to Source Charge	Q _{GS}			1.4		
Gate to Drain Charge	Q _{GD}			2.4		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 3A, R _{GEN} = 3Ω		5		ns
Rise Time	T _r			15		
Turn-off Delay Time	T _{D(OFF)}			22		
Fall Time	T _f			7		

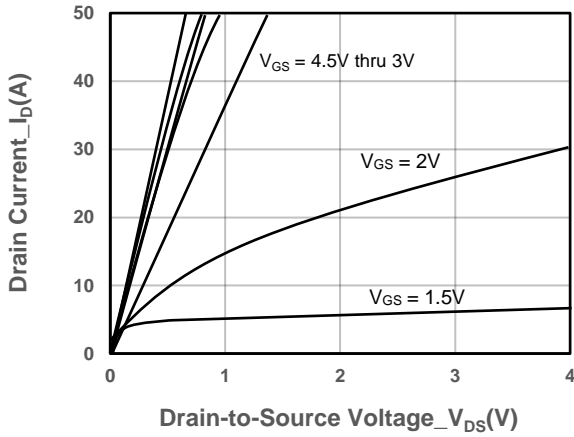


➤ **P-Channel Electrical Characteristics (T_A=25°C unless otherwise noted)**

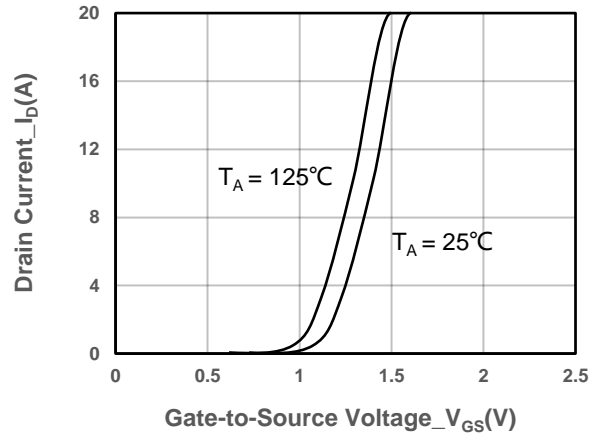
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250uA	-0.4	-0.68	-1	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -4.5V, I _D = -4A		24	33	mΩ
		V _{GS} = -2.5V, I _D = -3A		37	50	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -16V, V _{GS} = 0V			-1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = -2A		-0.82	-1.3	V
Input Capacitance	C _{ISS}	V _{DS} = -10V, V _{GS} = 0V, f = 1MHz		830		pF
Output Capacitance	C _{OSS}			190		
Reverse Transfer Capacitance	C _{RSS}			197		
Total Gate Charge	Q _G	V _{GS} = -4.5V, V _{DS} = -10V, I _D = -4A		15		nC
Gate to Source Charge	Q _{GS}			2.3		
Gate to Drain Charge	Q _{GD}			2.2		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = -4.5V, V _{DS} = -10V, R _L = 4Ω, R _{GEN} = 1Ω, I _D = -2.5A		10		ns
Rise Time	T _r			30		
Turn-off Delay Time	T _{D(OFF)}			20		
Fall Time	T _f			11		



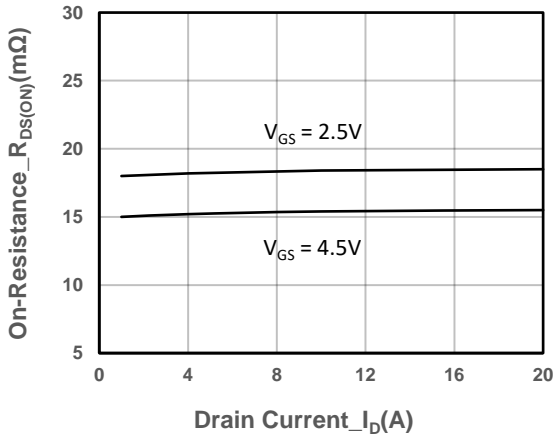
➤ N-Channel Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



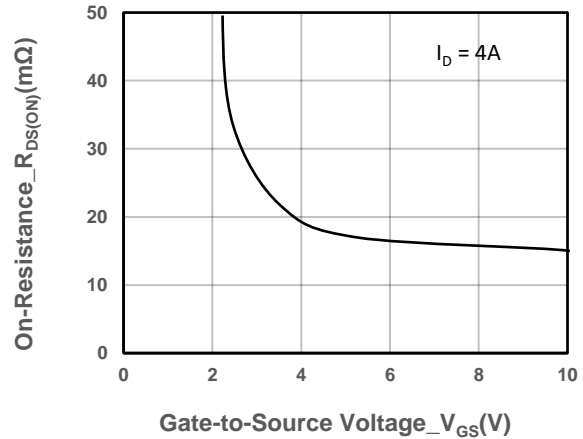
Output Characteristics



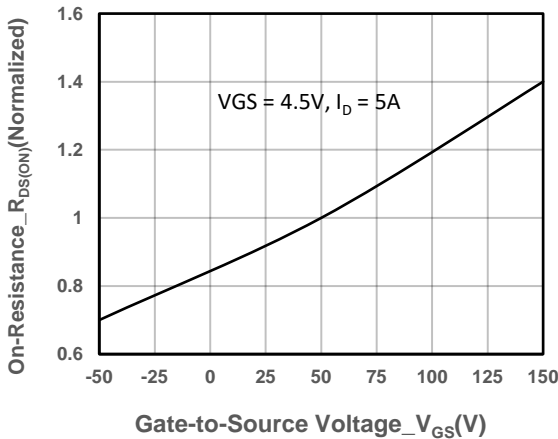
Transfer Characteristics



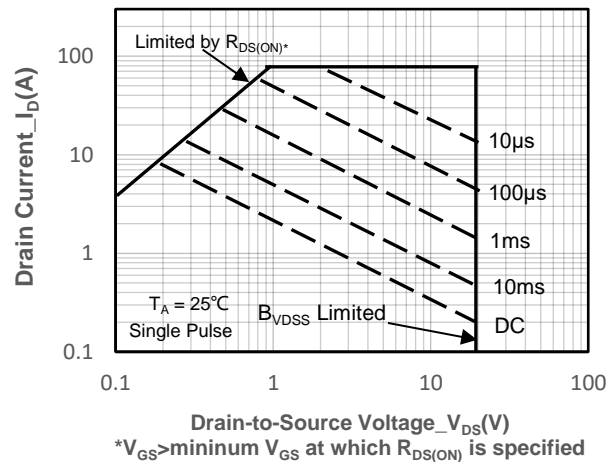
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage



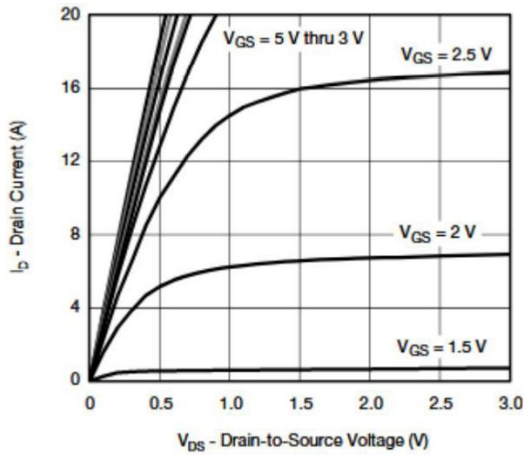
On-Resistance vs. Junction Temperature



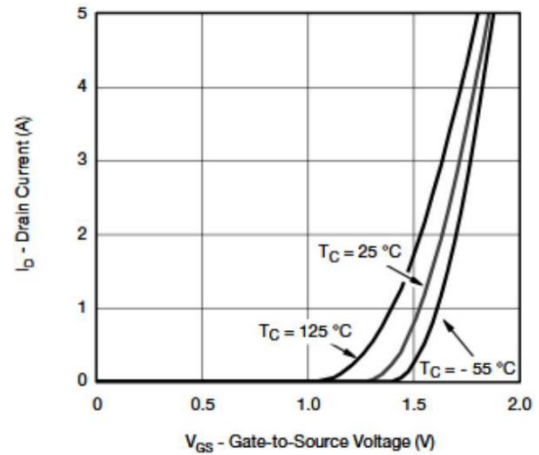
Safe Operating Area vs. Junction-to-Ambient



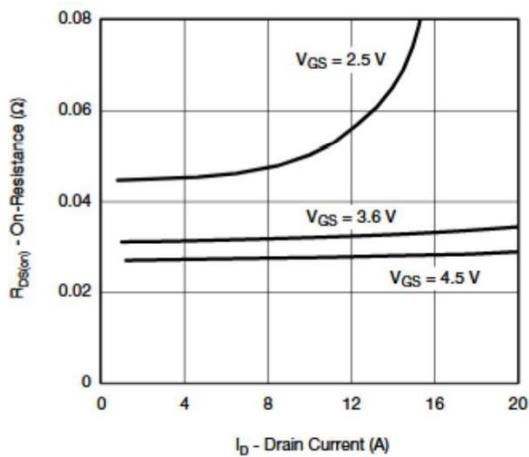
➤ P-Channel Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



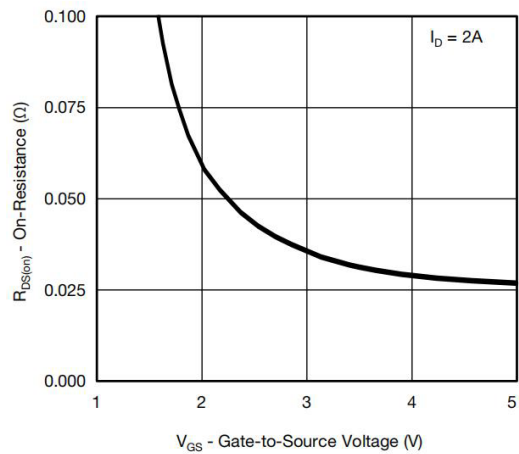
Output Characteristics



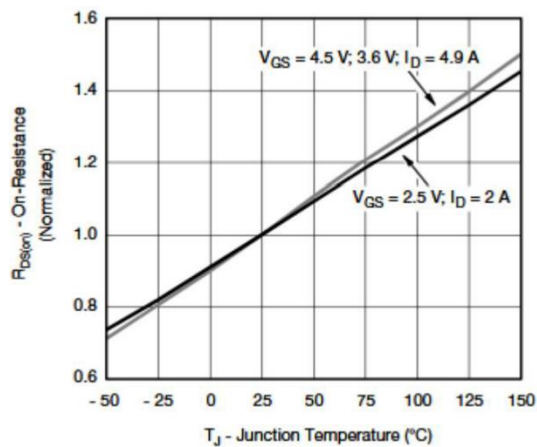
Transfer Characteristics



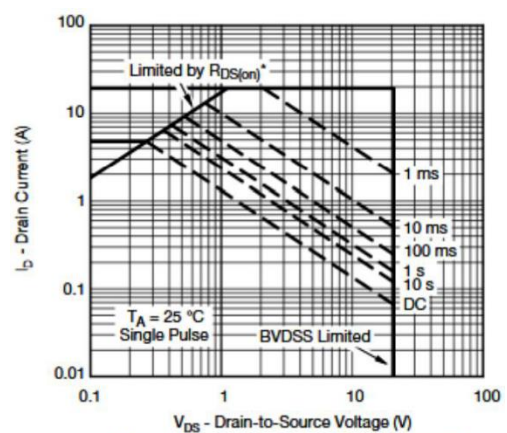
On Resistance vs. Drain Current



On-Resistance vs. Gate-to-Source Voltage



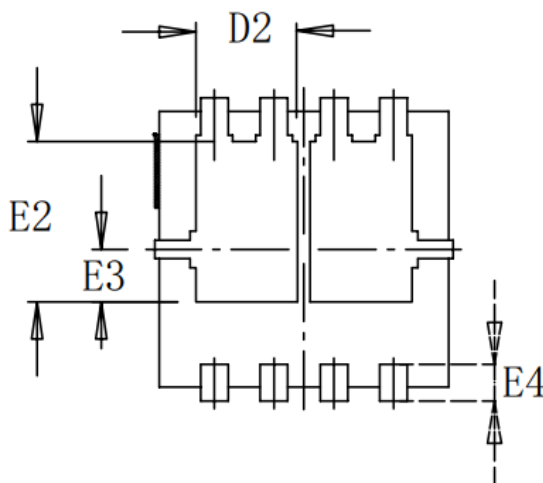
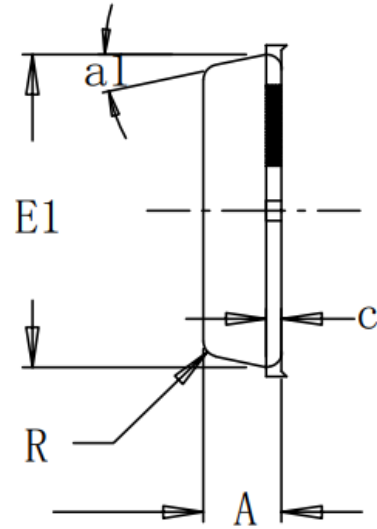
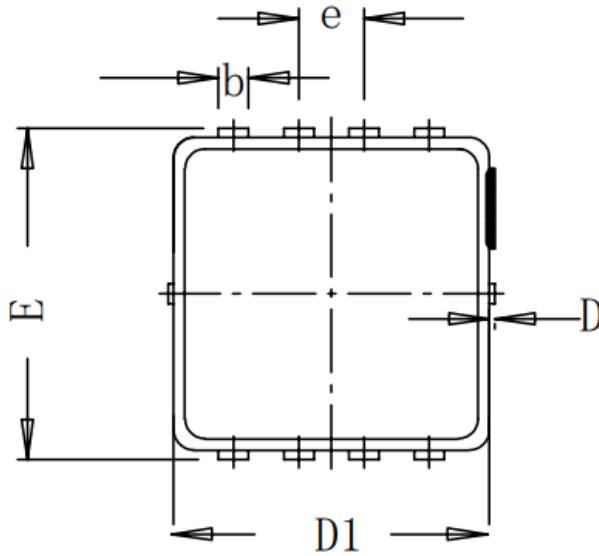
On-Resistance vs. Junction Temperature



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

➤ Package Information



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SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.75	0.78	0.81
b	0.297	0.3	0.35
c	—	0.152	—
D	0.00	0.05	0.1
D1	3.12	3.15	3.18
D2	—	1.05	—
E	3.2	3.3	3.4
E1	3.09	3.12	3.15
E2	—	1.75	—
E3	—	0.575	—
E4	—	0.4	—
R	—	0.15	—
e	0.65BSC		
a1°	—	12°	—



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